

ABSTRACT OF THE DISCLOSURE

A semiconductor chip which is to be overlapped with and joined to a surface of another solid device. The semiconductor chip has a surface protective film for covering internal wiring, an external connection pad which is formed by partially exposing the internal wiring from the surface protective film, and a wire connecting portion which is formed using a metal material having oxidation resistance on the external connection pad and to which a wire for electrical connection to an external terminal is connected. It is preferable that the semiconductor chip further has an internal connection pad used for connection to the solid device and a bump formed on the pad.

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